

IN THE SPECIFICATION:

Please replace paragraph [0011] of the specification with the following paragraph:

--[0011] However, in the LCD devices, pattern sizes differ according to different layers that are to be formed, and differ for the same layers. In addition, although the pattern sizes determine a viscosity of the resist to be used, resists of different viscosities cannot be printed at one time. Thus, a resist having viscosity suitable for a pattern of a corresponding size has to be selected. When using a resist suitable for a relatively small pattern, when the resist is filled into the grooves of the cliché and ~~the cliché~~ is flattened by the doctor blade, the resist is removed more easily at a center portion of the cliché than at edge portions of the cliché. Accordingly, the thickness of a pattern is not uniform.--

Please replace paragraph [0027] of the specification with the following paragraph:

--[0027] FIGS. 4A to 4E are schematic cross sectional views of an exemplary method of fabricating an LCD device according to the present invention. In FIG. 4A, a substrate 101 may be prepared, and then a buffer layer 103, such as a metal, an organic film, or silicon, may be deposited onto the substrate 101. Then, the buffer layer 103 may be patterned using photolithographic processes to fabricate a ~~cliché 103~~ cliché 100 having a plurality of grooves 105a, 105b, and 105c. The grooves 105a, ~~[[105n]]~~ 105b, and 105c are mask patterns used for forming a pattern of the LCD device. Since the pattern of the LCD device may be used for the same layer having various sizes, sizes of the grooves 105a, ~~[[105n]]~~ 105b, and 105c may have different dimensions and related intervals. For example, the first groove 105a may have a first width d1, the second groove 105b may

have a width d2 narrower than the width d1 of the first groove 105a, and the third groove 105c may have a width d3 wider than the width d1 of the first groove.--

Please replace paragraph [0029] of the specification with the following paragraph:

--[0029] In FIG. 4B, a resist material 131 may be deposited onto a surface of the cliché 100, and then ~~the surface of the cliché 100 may~~ flattened by using a doctor blade 132. Accordingly, the resist material 131 is filled only into the grooves 105a, 105b, and 105c and the resist material 131 that remains on the surface of the cliché 100 may be removed.--

Please replace paragraph [0034] from the specification with the following paragraph:

--[0034] In FIG. 4E, a resist pattern 106 may be formed on the substrate 130 using the resist material 131 (in FIG. 4D). Accordingly, the resist pattern may include first, second, and third resist patterns 106a, 106b, and 106c each having the same thickness regardless of a pattern size. The first resist pattern 106a may be formed by the resist material 131 filled into the first groove ~~[[105b]]~~ 105a (in FIG. 4C), and the second and third resist patterns 106b and 106c may be formed by the resist material 131 filled into the ~~first~~ second and ~~second~~ third grooves 105b and 105c (in FIG. 4C).--

Please replace paragraph [0035] of the specification with the following paragraph:

--[0035] Next, an etching object layer 135 ~~(not shown)~~ for forming a pattern may be formed on the substrate 130. The etching object layer 135 may be a metal layer for

forming a metal pattern, such as a gate electrode, source/drain electrodes, a gate line, a data line, a pixel electrode, and a storage electrode, or may be an insulating layer, such as SiO_x or SiN_x. The etching object layer may include an organic layer. --

Please replace paragraph [0037] of the specification with the following paragraph:

--[0037] FIGS. 5A to 5C schematic cross sectional views of another exemplary method of fabricating an LCD device according to the present invention. In FIG. 5A, a cliché 200, which may include a plurality of grooves 205a, 205b, and 205c, may be prepared. Then, a resist material 231 may be deposited onto a surface of the cliché 200. Next, the resist material 231 ~~surface of the cliché 200~~ may be flattened by using a doctor blade 232, thereby filling the plurality of grooves 205a, 205b, and 205c with the resist material 231 and removing any of the resist material 231 that remains on the surface of the cliché 200. Although not shown, the cliché 200 may comprise a substrate and a buffer layer.--